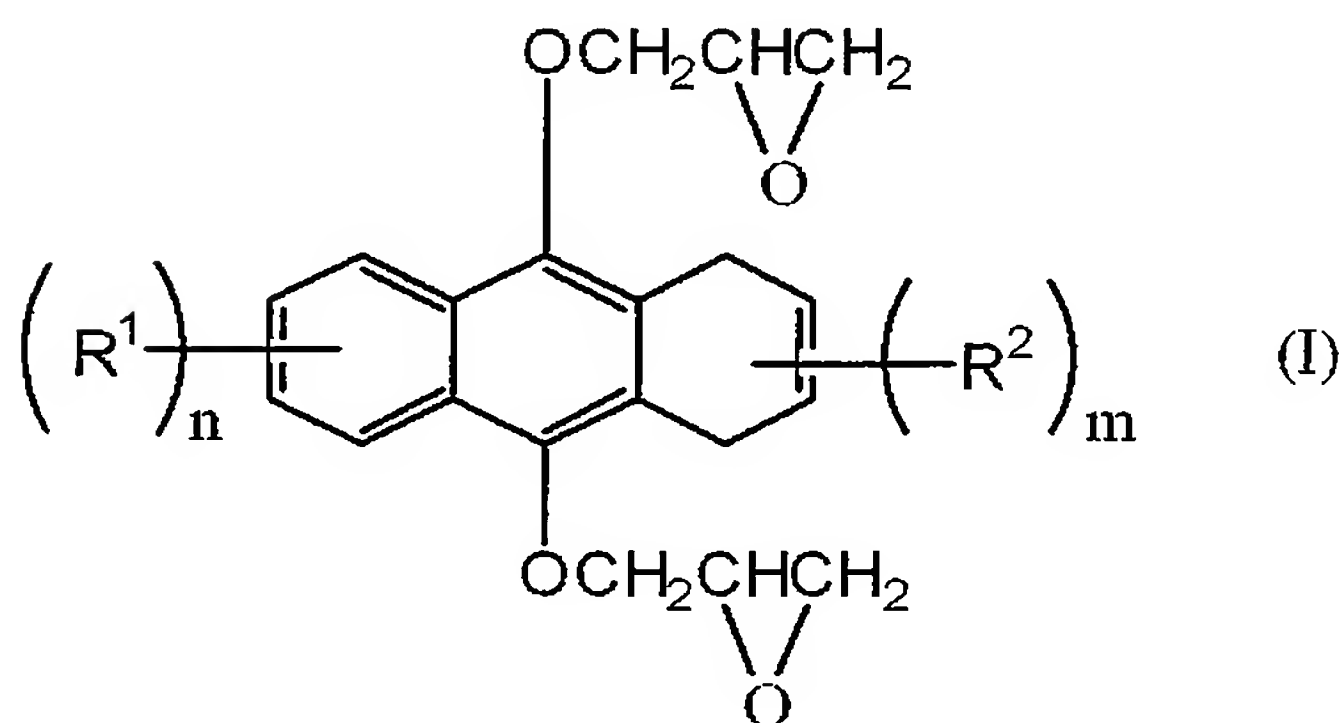


## CLAIMS

1. A sealant epoxy-resin molding material, comprising an epoxy resin (A) and a hardening agent (B), wherein the epoxy resin (A) contains a compound represented by the following General Formula (I):

[Formula 1]

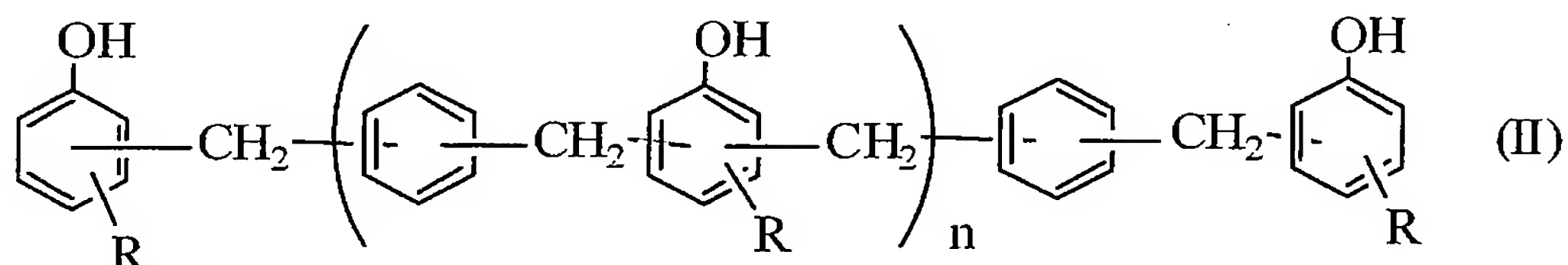


(in General Formula (I),  $\text{R}^1$  represents a group selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy groups having 1 to 12 carbon atoms, and the groups  $\text{R}^1$  may be the same as or different from each other;  $n$  is an integer of 0 to 4;  $\text{R}^2$  represents a groups selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy groups having 1 to 12 carbon atoms and the groups  $\text{R}^2$  may be the same as or different from each other; and  $m$  is an integer of 0 to 6).

2. The sealant epoxy-resin molding material according to Claim 1, wherein the hardening agent (B) contains a compound

represented by the following General Formula (II):

[Formula 2]



(wherein, R represents a group selected from a hydrogen atom and substituted or unsubstituted monovalent hydrocarbon groups having 1 to 10 carbon atoms; and n is an integer of 0 to 10).

3. The sealant epoxy-resin molding material according to Claim 1 or 2, further comprising a hardening accelerator (C).

4. The sealant epoxy-resin molding material according to Claim 3, wherein the hardening accelerator (C) is triphenylphosphine.

5. The sealant epoxy-resin molding material according to Claim 3, wherein the hardening accelerator (C) is an adduct of a tertiary phosphine compound and a quinone compound.

6. The sealant epoxy-resin molding material according to any one of Claims 1 to 5, further comprising an inorganic filler (D).

7. The sealant epoxy-resin molding material according to Claim 6, wherein the content of the inorganic filler (D) is 60

to 95 wt % with respect to the sealant epoxy-resin molding material.

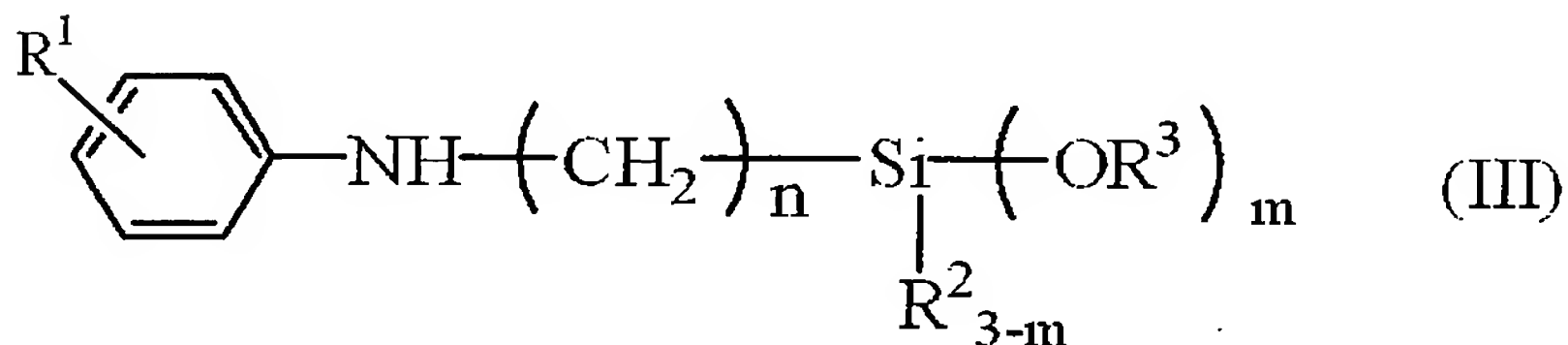
8. The sealant epoxy-resin molding material according to Claim 6 or 7, wherein the content of the inorganic filler (D) is 70 to 90 wt % with respect to the sealant epoxy-resin molding material.

9. The sealant epoxy-resin molding material according to any one of Claims 1 to 8, further comprising a coupling agent (E).

10. The sealant epoxy-resin molding material according to Claim 9, wherein the coupling agent (E) contains a secondary amino group-containing silane-coupling agent.

11. The sealant epoxy-resin molding material according to Claim 10, wherein the secondary amino group-containing silane-coupling agent contains a compound represented by the following General Formula (III):

[Formula 3]



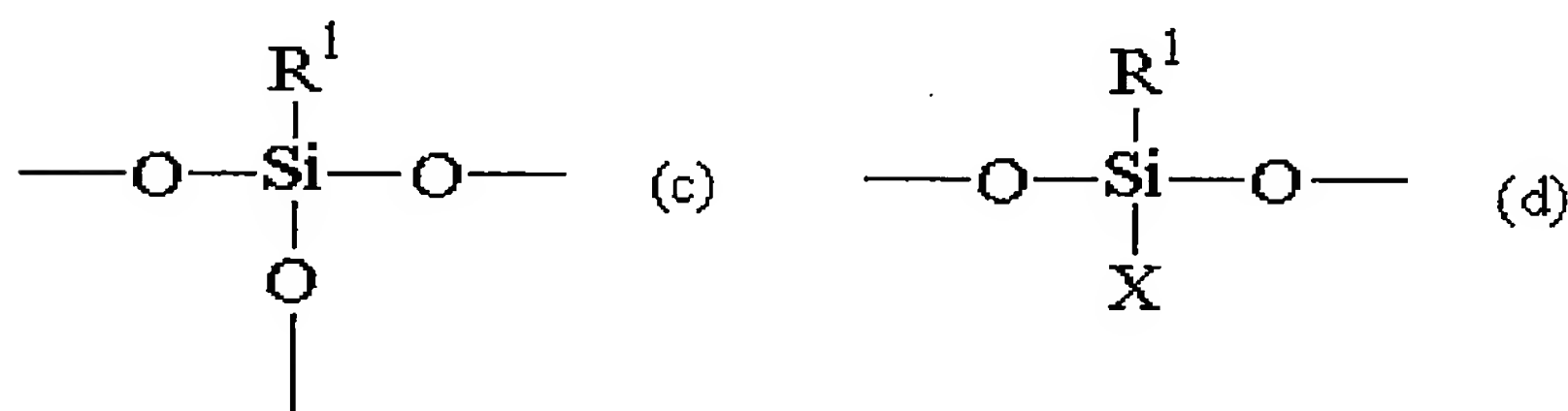
(wherein,  $\text{R}^1$  represents a group selected from a hydrogen atom, alkyl groups having 1 to 6 carbon atoms, and alkoxy group having 1 to 2 carbon atoms;  $\text{R}^2$  represents a group selected from alkyl groups having 1 to 6 carbon atoms and a phenyl group;  $\text{R}^3$

represents a methyl or ethyl group; n is an integer of 1 to 6; and m is an integer of 1 to 3).

12. The sealant epoxy-resin molding material according to any one of Claims 1 to 11, wherein the epoxy resin (A) and the hardening agent (B) are melt-mixed previously.

13. The sealant epoxy-resin molding material according to any one of Claims 1 to 12, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d), a terminal selected from  $R^1$ , a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000.

[Formula 4]



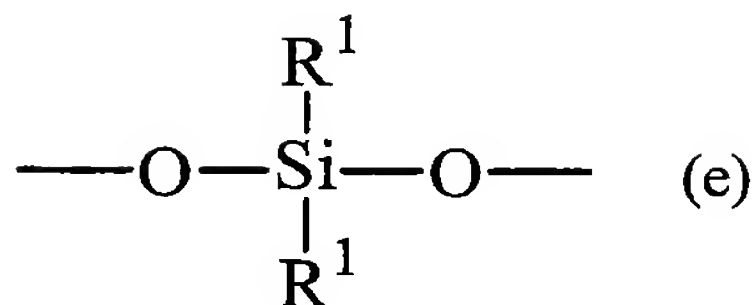
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(wherein,  $R^1$  represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms; the groups  $R^1$  in the silicon-containing polymer may be the same as or different from each other; and X represents an epoxy group-containing monovalent organic group).

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14. The sealant epoxy-resin molding material according to Claim 13, wherein the silicon-containing polymer (F) has the following bond (e) additionally:

[Formula 5]



(wherein,  $\text{R}^1$  represents a group selected from substituted  
 5 or unsubstituted monovalent hydrocarbon groups having 1 to 12  
 carbon atoms; and the groups  $\text{R}^1$  in the silicon-containing polymer  
 may be the same as or different from each other).

15. The sealant epoxy-resin molding material according to  
 10 Claim 13 or 14, wherein the softening temperature of the  
 silicon-containing polymer (F) is 40°C or higher and 120°C or lower.

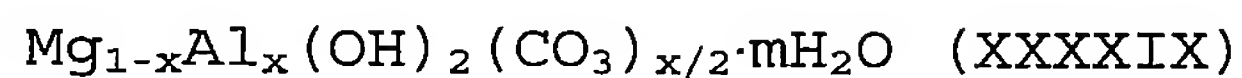
16. The sealant epoxy-resin molding material according to  
 any one of Claims 13 to 15, wherein  $\text{R}^1$  in the silicon-containing  
 15 polymer (F) is at least one of a substituted or unsubstituted phenyl  
 group and a substituted or unsubstituted methyl group.

17. The sealant epoxy-resin molding material according to  
 any one of Claims 13 to 16, wherein the rate of substituted or  
 20 unsubstituted phenyl groups having 1 to 12 carbon atoms in all  
 groups  $\text{R}^1$  in the silicon-containing polymer (F) is 60 to 100 mol %.

18. The sealant epoxy-resin molding material according to  
 any one of Claims 1 to 17, further comprising at least one of a  
 25 compound (G) represented by Compositional Formula (XXXXIX) and

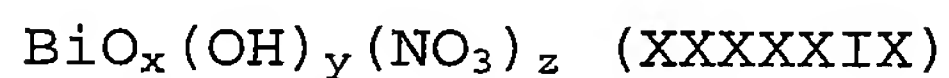
a compound (H) represented by the following Compositional Formula (XXXXXIX) :

(Formula 6)



5        ( $0 < x \leq 0.5$ ; and m is a positive number), and

(Formula 7)



( $0.9 \leq x \leq 1.1$ ,  $0.6 \leq y \leq 0.8$ , and  $0.2 \leq z \leq 0.4$ ).

10        19. An electronic component device, comprising an element sealed with the sealant epoxy-resin molding material according to any one of Claims 1 to 18.